Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	8.00mil	4.2	
5	POWER	Copper	1.40mil		
6	Dielectric 2	FR-4	40.00mil	4.2	
7	GND	Copper	1.40mil		
8	Dielectric 3	FR-4	8.00mil	4.2	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

ZZ1 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
ZZ2 ■ This Assembly Note will show in the PcbDoc and associated outputs
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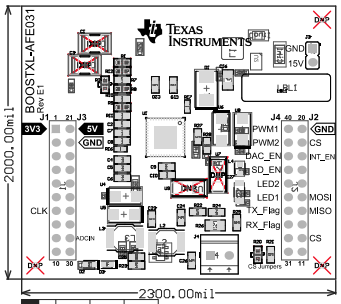

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED
ASSEMBLY VARIANT: DAC_Mode

DESIGN INFORMATION	
MIN. TRACK WIDTH:	8 MIL
MIN. CLEARANCE:	0.2 mm
MIN. VIA PAD SIZE:	24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [ ] GREEN [X] OTHER RED
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

PROJECT TITLE:	BOOSTXL-PARTNUM
DESIGNED FOR:	Public Release
FILE NAME:	AFE031-BOOSTXL_PCB.PcbDoc
ENGINEER:	Enter name of project
LAYOUT BY:	Who did the Layout?
SCALE:	0.71
ALTIUM DESIGNER VERSION:	17.1.9.592

LAYER NAME =	Assembly Drawing	BOARD	BoosterPack	REV:	E1
PLOT NAME =	Assembly Drawing	GENERATED	3/23/2018	TEXAS INSTRUMENTS	

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
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MIN. VIA PAD SIZE:	24 MIL
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REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL	
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED):	+/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [ ] GREEN [X] OTHER RED
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE
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ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

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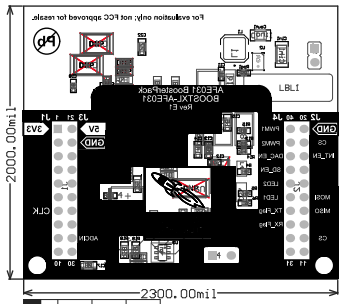

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TEXAS INSTRUMENTS

PROJECT TITLE: BOOSTXL-PARTNUM
DESIGNED FOR: Public Release
FILE NAME: AFE031-BOOSTXL_PCB.PcbDoc

ENGINEER: Enter name of project	LAYOUT BY: Who did the Layout?
SCALE: 0.71	ALTIUM DESIGNER VERSION: 17.1.9.592

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
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DESIGN INFORMATION	
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HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED):	+/- 3 MIL

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THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
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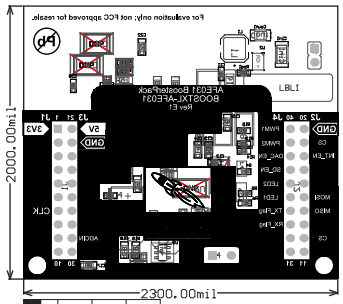

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TEXAS INSTRUMENTS

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FILE NAME: AFE031-BOOSTXL_PCB.PcbDoc

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SCALE: 0.71	ALTIUM DESIGNER VERSION: 17.1.9.592

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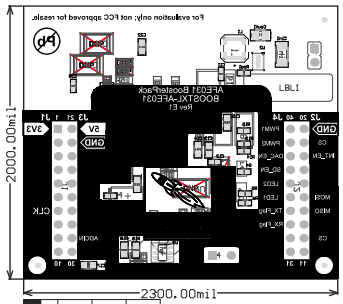

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ASSEMBLY VARIANT: DAC_Mode

DESIGN INFORMATION

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MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
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MATERIAL:
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[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
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DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER
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ADDITIONAL REQUIREMENTS:
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TEXAS INSTRUMENTS

PROJECT TITLE: BOOSTXL-PARTNUM
DESIGNED FOR: Public Release
FILE NAME: AFE031-BOOSTXL_PCB.PcbDoc

ENGINEER: Enter name of project	LAYOUT BY: Who did the Layout?
SCALE: 0.71	ALTIUM DESIGNER VERSION: 17.1.9.592

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